

ON Semiconductor			10/15/2019	
Base Part		FQD6N50C	HF	
Orderable Part		FQD6N50CTM	Total weight (mg)	329.241
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	5.16	Silicon (Si)	7440-21-3	100
Die Attach Solder	5.026	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	167.854	Tin (Sn)	7440-31-5	0.10008698
		Nickel (Ni)	7440-02-0	0.10008698
		Copper (Cu)	7440-50-8	99.79982604
Mold Compound-Black	149.268	Ortho Cresol Novolac Resin	29690-82-2	7.49993301
		Carbon Black (C)	1333-86-4	0.49977222
		Fused Silica (SiO2)	60676-86-0	83.00037516
		Phenolic Resin (Novolac)	9003-35-4	8.99991961
Plating	1.092	Tin (Sn)	7440-31-5	100
Wire Bond - Al	0.841	Aluminum (Al)	7429-90-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				